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### SEMICONDUCTOR DEVICE HAVING AIR GAP AND METHOD OF FABRICATING THEREOF

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#### Abstract

Methods and devices that provide for a fin structure and a dielectric fin structure. A gate structure is formed over the fin structure and the hybrid fin structure. A plurality of dielectric layers is adjacent the gate structure and over the hybrid fin structure between the gate structure and a contact element over the dielectric fin structure. The plurality of dielectric layers includes an air gap, formed by removal of a dummy spacer layer.

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## Background/Summary

CROSS-REFERENCE TO RELATED APPLICATIONS [0001] This application is a divisional application of U.S. patent application Ser. No. 17/446,419, filed Aug. 30, 2021, the entire disclosure of which is incorporated herein by reference.

### BACKGROUND

[0002] The electronics industry has experienced an ever-increasing demand for smaller and faster electronic devices which are simultaneously able to support a greater number of increasingly complex and sophisticated functions. Accordingly, there is a continuing trend in the semiconductor industry to manufacture low-cost, high-performance, and low-power integrated circuits (ICs). Thus far these goals have been achieved in large part by scaling down semiconductor IC dimensions (e.g., minimum feature size) and thereby improving production efficiency and lowering associated costs. However, such scaling has also introduced increased complexity to the semiconductor manufacturing process. Thus, the realization of continued advances in semiconductor ICs and devices calls for similar advances in semiconductor manufacturing processes and technology.

[0003] Recently, multi-gate devices have been introduced in an effort to improve gate control by increasing gate-channel coupling, reduce OFF-state current, and reduce short-channel effects (SCEs). One such multi-gate device that has been introduced is the fin field-effect transistor (FinFET). The FinFET gets its name from the fin-like structure which extends from a substrate on which it is formed, and which is used to form the FET channel. FinFET devices enable aggressive scaling down of IC technologies, maintaining gate control and mitigating SCEs, while seamlessly integrating with conventional IC manufacturing processes. However, as semiconductor devices continue to scale, challenges arise in achieving desired density and performance. For example, addressing capacitance between adjacent conductive features of a device is needed to affecting device performance, for example, providing a desired operating speed. Accordingly, although existing devices and methods for fabricating such have been generally adequate for their intended purposes, they have not been entirely satisfactory in all respects.

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## Description

### BRIEF DESCRIPTION OF THE DRAWINGS

[0004] Aspects of the present disclosure are best understood from the following detailed description when read with the accompanying figures. It is noted that, in accordance with the standard practice in the industry, various features are not drawn to scale. In fact, the dimensions of the various features may be arbitrarily increased or reduced for clarity of discussion.

[0005] FIG. 1 is a flow chart of a method of fabricating a semiconductor device providing an air spacer adjacent a hybrid fin according to one or more aspects of the present disclosure;

[0006] FIG. 2 is a top view of a multi-gate device according to one or more aspects of the present disclosure;

[0007] FIGS. 3A, 3B, 4A, 4B, 5A, 5B, 6A, 6B, 7A, 7B, 8A, 8B, 9A, 9B, 10A, 10B, 11A, 11B, 12A, 12B, 13A, 13B, 14A, 14B, 15A, 15B, 16A, 16B, 17A, 17B, 18A, 18B, 19A, 19B, 20A, 20B, 21A, 21B, 22A, 22B, 23A, 23B, 24A, 24B, 25A, and 25B provide cross-sectional views of an exemplary semiconductor device fabricated according to one or more steps of the method of FIG. 1;

[0008] FIGS. 26A and 26B provide an alternative embodiment of an exemplary semiconductor device that may be fabricated according to one or more steps of the method of FIG. 1; and [0009] FIGS. 27A and 27B provide another alternative embodiment of an exemplary [0010] semiconductor device that may be fabricated according to one or more steps of the method of FIG. 1.

## DETAILED DESCRIPTION

[0011] The following disclosure provides many different embodiments, or examples, for implementing different features of the provided subject matter. Specific examples of components and arrangements are described below to simplify the present disclosure. These are, of course, merely examples and are not intended to be limiting. For example, the formation of a first feature over or on a second feature in the description that follows may include embodiments in which the first and second features are formed in direct contact, and may also include embodiments in which additional features may be formed between the first and second features, such that the first and second features may not be in direct contact. In addition, the present disclosure may repeat reference numerals and/or letters in the various examples. This repetition is for the purpose of simplicity and clarity and does not in itself dictate a relationship between the various embodiments and/or configurations discussed.

[0012] Further, spatially relative terms, such as “beneath,” “below,” “lower,” “above,” “upper” and the like, may be used herein for ease of description to describe one element or feature's relationship to another element(s) or feature(s) as illustrated in the figures. The spatially relative terms are intended to encompass different orientations of the device in use or operation in addition to the orientation depicted in the figures. The apparatus may be otherwise oriented (rotated 90 degrees or at other orientations) and the spatially relative descriptors used herein may likewise be interpreted accordingly.

[0013] It is also noted that the present disclosure presents embodiments in the form of multi-gate transistors or fin-type multi-gate transistors referred to herein as FinFET devices. Such a device may include a P-type metal-oxide-semiconductor FinFET device or an N-type metal-oxide-semiconductor FinFET device. The FinFET device may be a dual-gate device, tri-gate device, bulk device, silicon-on-insulator (SOI) device, and/or other configuration. One of ordinary skill may recognize other embodiments of semiconductor devices that may benefit from aspects of the present disclosure. For example, some embodiments as described herein may also be applied to gate-all-around (GAA) devices, Omega-gate ( $\Omega$ -gate) devices, or Pi-gate ( $\Pi$ -gate) devices. In each case an active region for example having a structure of a “fin” is provided and an adjacent isolation structure, similarly having a structure of a “fin,” but comprising dielectric materials may separate active regions.

[0014] In FIG. 1, illustrated is a method **100** of fabricating a semiconductor device (e.g., such as that including a plurality of FinFET devices), in accordance with one or more embodiments. In some embodiments, the method **100** may be used to fabricate the device **200**, described below with reference to FIGS. 2-25B. It is understood that parts of the method **100** and/or the semiconductor device **200** may be fabricated by a well-known CMOS technology process flow, and thus some processes are only briefly described herein.

[0015] The method **100** begins at block **102** where a semiconductor structure is received, the semiconductor structure having a plurality of active fins and a plurality of hybrid fins (also referred to as dielectric fins and/or dummy fins). The active fins are fin-element structures that vertically extend above a semiconductor structure and provide elements of semiconductor devices, such as a channel region. The hybrid fins are fin-element structures comprising dielectric material that likewise vertically extend above a semiconductor substrate, but do not include a channel of an active device (e.g., transistor). The hybrid fins may be formed within a region of the device for a given device type (e.g., PMOS) and/or may be formed at a boundary between areas of different device types (e.g., a boundary between NMOS and PMOS devices).

[0016] Illustrated in FIG. 2 illustrates a schematic top-view a semiconductor device **200**. In an embodiment, the semiconductor device **200** includes one or more fin-based, multi-gate field-effect transistors (FETs). The semiconductor device is formed on a substrate **202** and includes a plurality of fin-elements **206** extending vertically above the substrate **202** and extending in a first (x-axis) direction. The fin-elements **206** provide the active regions of the semiconductor device. The semiconductor device **200** also includes a plurality of hybrid fins **208**, which may also be referred to as dielectric fins or dummy fins. The hybrid fins **208** comprise dielectric material and do not include a channel of an active device (e.g., transistor). A plurality of gate structures or lines **210** run orthogonal to the active fins **206** and hybrid fins **208**. The gate structure **210** is formed on and around the fin-elements **206** and **208**. A FET is formed where a gate structure **210** overlaps the active regions of the fin element **206**. In some embodiments, isolation features **204** extend between the fin structures.

[0017] The substrate **202** may be a semiconductor substrate such as a silicon substrate. The substrate **202** may include various layers, including conductive or insulating layers formed on a semiconductor substrate. The substrate **202** may include various doping configurations depending on design requirements as is known in the art. The substrate **202** may also include other semiconductors such as germanium, silicon carbide (SiC), silicon germanium (SiGe), or diamond. Alternatively, the substrate **202** may include a compound semiconductor and/or an alloy semiconductor. Further, in some embodiments, the substrate **202** may include an epitaxial layer (epi-layer), the substrate **202** may be strained for performance enhancement, the substrate **202** may include an SOI structure, and/or the substrate may have other suitable enhancement features.

[0018] The fin structure **206**, like the substrate **202**, may comprise silicon or another elementary semiconductor, such as germanium; a compound semiconductor including silicon carbide, gallium arsenide, gallium phosphide, indium phosphide, indium arsenide, and/or indium antimonide; an alloy semiconductor including SiGe, GaAsP, AlInAs, AlGaAs, InGaAs, GaInP, and/or GaInAsP; or combinations thereof. The fins **206** may be fabricated using suitable processes including photolithography and etch processes. The photolithography process may include forming a photoresist layer (resist) overlying the substrate (e.g., on a silicon layer), exposing the resist to a pattern, performing post-exposure bake processes, and developing the resist to form a masking element including the resist. In some embodiments, patterning the resist to form the making element may be performed using an electron beam (e-beam) lithography process. The masking element may then be used to protect regions of the substrate, while an etch process forms recesses into the substrate (e.g., silicon) layer, thereby leaving an extending fin **206**. The recesses may be etched using a dry etch (e.g., chemical oxide removal), a wet etch, and/or other suitable processes. Numerous other embodiments of methods to form the fins **206** on the substrate **202** may also be used.

[0019] Each of the plurality of fins **206** also include a source region and a drain region, where the source/drain regions will be formed in, on, and/or surrounding the fin **206** in the source/drain regions which are disposed on opposing sides of the gate structure **210** as discussed below. A channel region of a transistor is disposed within the fin **206**, underlying the gate structure **210**.

[0020] The isolation regions **204** may be shallow trench isolation (STI) features. Alternatively, a field oxide, a LOCOS feature, and/or other suitable isolation features may be implemented on and/or within the substrate **202**. The isolation regions **204** may be composed of silicon oxide, silicon nitride, silicon oxynitride, fluorine-doped silicate glass (FSG), a low-k dielectric, combinations thereof, and/or other suitable material. In an embodiment, the isolation structures are STI features and are formed by etching trenches in the substrate **202**. The trenches may then be filled with isolating material, followed by a chemical mechanical polishing (CMP) process. However, other embodiments are possible. In some embodiments, the isolation regions **204** may include a multi-layer structure, for example, having one or more liner layers.

[0021] Hybrid fins **208** include isolation materials and are similarly shaped to the active fins **206**.

The hybrid fins **208** may differ in width from the active fins **206**. In some examples, the hybrid fins **208** may be formed after the fins **206**. For example, in some embodiments, the isolation regions **204** interposing the fins **206** may be patterned (e.g., using a photolithography and etching process) to form trenches within the isolation regions **204** and within which the hybrid fins **208** will be formed. Alternatively, the dielectric material used to form the isolation regions **204** may be deposited conformally over the fins **206**, such that the conformal deposition itself forms trenches within the isolation regions **204** and between adjacent fins **206**, within which the hybrid fins **208** will be formed. Regardless of how they are fabricated, one or more isolation materials are used to form the hybrid fins **208**. In some cases, the isolation material used to form the hybrid fins **208** may include a layer of a low-K (LK) material including SiCN, SiOC, SiOCN, or another low-K material (e.g., with a dielectric constant ' $k$ ' < 7) and a layer of a high-K (HK) material including HfO<sub>2</sub>, ZrO<sub>2</sub>, HfAlO<sub>x</sub>, HfSiO<sub>x</sub>, Al<sub>2</sub>O<sub>3</sub>, or another high-K material (e.g., with a dielectric constant ' $k$ ' > 7). For example, in some embodiments, the isolation material used to form the hybrid fins **208** may include a first layer and a second layer formed over the first layer, where the first layer includes a dielectric material (such as LK material or oxide), and where the second layer includes a HK material (such as a HK material noted above). In some embodiments, hybrid fins **208** may effectively prevent the undesirable lateral merging of the source/drain feature (e.g., epitaxially grown layers) formed on adjacent fins **206**.

[0022] FIG. 3B illustrates a hybrid fin **208** having a first layer **208B** and an overlying second layer **208A**. In an embodiment, the second layer **208A** is a HK material. Exemplary compositions for the second layer **208A** include HfO, LaO, AlO, LaO, ZnO, YO, ZrAlO, TiO, TaO, ZrO, combinations thereof, and/or other suitable materials. The first layer **208B** may comprise a different dielectric material, for example, that has a lower dielectric constant. In some implementations, the first layer **208B** is a low-K material such as a material including silicon and nitrogen.

[0023] Returning to FIG. 2, illustrated are gate structure **210**. The gate structure **210** may be substantially similar to the dummy gate structure discussed below and/or the metal gate structure of the final semiconductor device. The gate structure **210** includes a gate stack having a gate dielectric layer, and an electrode layer formed over the gate dielectric layer as discussed in further detail below. The composition of the gate structure **210** may vary as to whether it is intended to form the gate of an n-type transistor or a p-type transistor.

[0024] In that respect, the semiconductor device **200** may include n-type transistors (NFET) and p-type transistors (PFET). For example, some fins **206** or portions thereof may be suitable for NMOS transistor device formation, while other fins **206** or portions thereof may be suitable for PMOS transistor device formation. Further, the semiconductor device **200** may include various other devices and features, such as additional transistors, bipolar junction transistors, resistors, capacitors, diodes, fuses, etc., but is simplified for a better understanding of the inventive concepts of the present disclosure. Further, in some embodiments, the semiconductor device **200** includes a plurality of semiconductor devices (e.g., transistors), which may be interconnected. Various contacts (not shown) may extend from the device features to overlying multi-layer interconnect (MLI). An MLI electrically couples various devices (for example, p-type transistors and/or n-type transistors of the device **200**, resistors, capacitors, and/or inductors) and/or components (for example, gate electrodes and/or epitaxial source/drain features of p-type transistors and/or n-type transistors of the device **200**), such that the various devices and/or components can operate as specified by design requirements of the device **200**. MLI feature includes a combination of dielectric layers and electrically conductive layers (e.g., metal layers) configured to form various interconnect structures. The conductive layers are configured to form vertical interconnect features, such as device-level contacts and/or vias, and/or horizontal interconnect features, such as conductive lines. Vertical interconnect features typically connect horizontal interconnect features in different layers (or different planes) of MLI feature. The contact elements and/or conductive vias discussed below may be included in the MLI feature. During operation, the interconnect features

are configured to route signals between the devices and/or the components of the device **200** and/or distribute signals (for example, clock signals, voltage signals, and/or ground signals) to the devices and/or the components of the device **200**. In various embodiments, the device **200** may be an intermediate device fabricated during processing of an integrated circuit, or portion thereof, that may comprise static random access memory (SRAM) and/or other logic circuits, passive components such as resistors, capacitors, and inductors, and active components such as P-channel field-effect transistors (PFETs), N-channel FETs (NFETs), metal-oxide-semiconductor field-effect transistors (MOSFETs), high voltage transistors, high frequency transistors, other memory cells, and/or combinations thereof.

[0025] Three cross-sectional cut markings are provided on the schematic top view of the device **200** in FIG. 2. Cross-sectional cut A-A' provides a cut along the active fin-element **206**; cross-sectional cut B-B' provides a cut along the hybrid fin-element **208** of the same gate structure as cut A-A'; cross-sectional cut B1-B1' provides a cut along the hybrid fin-element **208** of a different gate structure as cut A-A'. Each of the following Figures denoted "A" correspond to the A-A' on-fin cut (e.g., FIGS. 3A, 4A, 5A and so forth). Each of the following Figures denoted "B" correspond to the on-hybrid fin cuts (e.g., FIGS. 3B, 4B, 5B, and so forth). It is noted that the Figures corresponding to the "B" are illustrative of both the cut B-B' and the cut B1-B1'.

[0026] In block **104** of the method **100**, a dummy gate structure is formed over the active regions (e.g., fins) and the hybrid fins. The dummy gate structure refers to a sacrificial structure that mimics the structure of the to-be formed functional gate in a subsequent processing step, see block **112**. For example, the dummy gate structure has the dimensions of the final gate, but does not provide for current flow. Referring to the example of FIGS. 2, 3A, and 3B, a gate structure **210** providing a dummy gate structure is formed over fin **206** and the hybrid fin **208**. The dummy gate structure includes a gate dielectric layer **214**, a gate electrode layer **212**, and a hard mask layer(s) **216**. In an embodiment, the gate dielectric is an oxide material, however other dielectric compositions are also possible including high-k dielectric materials. In an embodiment, the gate electrode layer **212** is polysilicon, however other compositions may also be possible. The hard mask layer **216** is provided for suitable protective and patternable material (e.g., silicon nitride, silicon carbide) and may include multiple layers.

[0027] In some embodiments, the gate structure **210** may be formed by various process steps such as layer deposition, patterning, etching, as well as other suitable processing steps. Exemplary layer deposition processes include low-pressure CVD, CVD, plasma-enhanced CVD (PECVD), PVD, ALD, thermal oxidation, e-beam evaporation, or other suitable deposition techniques, or combinations thereof. The gate structure **210** may be provided by this deposition of materials (e.g., gate dielectric, gate electrode and hard mask materials), followed by a suitable patterning process may include a lithography process (e.g., photolithography or e-beam lithography) which may further include photoresist coating (e.g., spin-on coating), soft baking, mask aligning, exposure, post-exposure baking, photoresist developing, rinsing, drying (e.g., spin-drying and/or hard baking), other suitable lithography techniques, and/or combinations thereof. In some embodiments, the etching process to form the gate structure **210** may include dry etching (e.g., RIE etching), wet etching, and/or other etching methods.

[0028] After patterning of the dummy gate structure, spacer elements **218** are formed on the sidewall of the structure. In an embodiment, a first spacer element **218A** and a second spacer element **218B** are provided, however other configurations may also be possible. The first spacer element **218A** may be a L-shaped spacer abutting the sidewall of the gate structure **210**. The second spacer element **218B** is disposed over and on the first spacer element **218A**.

[0029] The spacer elements **218** include dielectric material including silicon, oxygen, carbon, nitrogen, other suitable material, or combinations thereof (for example, silicon oxide, silicon nitride, silicon oxynitride, or silicon carbide). In an implementation, the spacer element **218A** is silicon nitride and the spacer element **218B** is an oxide, such as silicon oxide. Other exemplary

compositions for the spacer element **218** generally and the spacer element **218A** in particular are HfSi, AlON, HfO, LaO, AlO, LaO, ZrN, SiC, ZnO, SiOC, SiOCN, YO, TaCN, ZrSi, SiCN, ZrAlO, TiO, TaO, ZrO, and/or combinations thereof. The spacer elements **218** may be formed after patterning the gate structure **210** by layer deposition processes include low-pressure CVD, CVD, plasma-enhanced CVD (PECVD), PVD, ALD, thermal oxidation, e-beam evaporation, or other suitable deposition techniques, or combinations thereof followed by suitable etching back processes (e.g., anisotropic etching processes). The spacer element **218A** and/or the spacer element **218B** may have a thickness of between approximately 1 nanometer (nm) and approximately 10 nm. The spacer elements **218** may have a configuration defining a low-dose source/drain area and/or provide sidewalls for a trench during the gate removal process discussed below.

[0030] The method **100** then proceeds to block **106** where portions of the active fin and hybrid fin are recessed in the respective source/drain regions. (It is noted that while a source/drain structure is not formed on the hybrid fin, for ease of reference the corresponding position of the source/drain—e.g., adjacent opposing sides of the gate, is referred to as the source/drain region.) Referring to the example of FIGS. **4A** and **4B**, recesses **402A** are formed in the fin **206** adjacent the gate structure **210** and recesses **402B** are formed in the hybrid fin **208** adjacent the gate structure **210**. In some implementations, the fin **206** is etched concurrently with the etching of the dielectric layer **208A** of the hybrid fin **208**. The recessing may be performed by suitable etching process such as a plasma-based dry etching.

[0031] The method **100** then proceeds to block **108** where an epitaxial source/drain region is grown on the recessed active fin. Because the recessed portion of the hybrid fin is dielectric material, epitaxial growth may not occur on the hybrid fin. In some implementations, a masking layer covers the hybrid fin during the epitaxial growth process. Referring to the example of FIGS. **5A** and **5B**, an epitaxial source/drain feature **502** is formed on the recessed fin **206**. The epitaxial source/drain feature **502** may be suitably doped such as by N-type dopants or P-type dopants based on the device. Exemplary compositions include Si:P, Si:C:P, Si:As, Si:C, SiGe, SiGe:B, and/or other suitable materials. Exemplary epitaxy techniques include but are not limited to CVD deposition techniques (e.g., vapor-phase epitaxy (VPE) and/or ultra-high vacuum CVD (UHV-CVD)), molecular beam epitaxy (MBE), and/or other suitable processes. As illustrated in FIG. **5B**, the recess **402B** is maintained on the hybrid fin **208**.

[0032] The method **100** then proceeds to block **110** where dielectric layers such as an inter-layer dielectric (ILD) and contact etch stop layer (CESL) are formed over the device and the epitaxial source/drain regions of block **108**. Referring to the example of FIGS. **6A** and **6B**, a CESL **604** and an ILD layer **606** are formed. ILD layer **606** includes a dielectric material including, for example, silicon oxide, carbon doped silicon oxide, silicon nitride, silicon oxynitride, TEOS-formed oxide, PSG, BSG, BPSG, FSG, Black Diamond® (Applied Materials of Santa Clara, California), xerogel, aerogel, amorphous fluorinated carbon, parylene, BCB-based dielectric material, SILK (Dow Chemical, Midland, Michigan), polyimide, other suitable dielectric material, or combinations thereof. In some embodiments, ILD layer **606** includes a dielectric material having a dielectric constant that is less than a dielectric constant of silicon dioxide (e.g.,  $k < 3.9$ ). In some embodiments, ILD layer **606** includes a dielectric material having a dielectric constant that is less than about 2.5 (i.e., an extreme low-k (ELK) dielectric material), such as SiO<sub>2</sub> (for example, porous silicon dioxide), silicon carbide (SiC), and/or carbon-doped oxide (for example, a SiCOH-based material (having, for example, Si—CH<sub>3</sub> bonds)), each of which is tuned/configured to exhibit a dielectric constant less than about 2.5. ILD layer **606** can include a multilayer structure having multiple dielectric materials. The CESL **604** may include a different dielectric material than the ILD layer, for example, the CESL **604** may be comprised of silicon and nitrogen, such as silicon nitride or silicon oxynitride. In some implementations, the materials of the CESL **604** and/or the ILD **606** are deposited by deposition processes (such as CVD, PVD, ALD, HDPCVD, MOCVD, RPCVD, PECVD, LPCVD, ALCVD, APCVD, FCVD, HARP, HDP, other suitable

methods, or combinations thereof). After deposition, a planarization process such as chemical mechanical polish (CMP) is performed to planarize the layers and expose a top portion of the gate structure **210** (e.g., gate electrode **212**).

[0033] In some implementations of the block **110**, the dummy structure is then removed providing for an opening or trench **602** as part of a replacement gate process. The gate dielectric **214** and/or the gate electrode **212** may be removed by an etching process such as a dry etching process, a wet etching process, or a combination thereof that is selective to the gate dielectric **214** and/or the gate electrode **212** materials. In an embodiment, the fin structure **206** (channel region) is exposed by the removal of the gate structure over the fin **206**. The gate structure may be removed from the hybrid fin **208** exposing the first layer **208A**. In an embodiment, because of a height difference between the hybrid fin **208** and the fin **206**, and thus a height difference in the gate structure (e.g., gate electrode **212**), the etching process sufficient to remove the gate structure from the fin **206** over etches the hybrid fin **208** creating the trench **602** extending into the layer **208A**. In an embodiment, the etching process that removes the gate structure over the hybrid fin **208** includes a recessing of the dielectric material **208A** with the dielectric material **208B** acting as an etch stop layer.

[0034] The method **100** then proceeds to block **112**, where the replacement gate process continues and a metal gate structure is formed in the openings provided by the removal of the dummy gate structures.

[0035] Referring to the example of FIGS. 7A and 7B, metal gate structures **702** (also referred to as metal gates and/or high-k/metal gates) are formed in gate openings **602**. Metal gate structures **702** are configured to achieve desired functionality according to design requirements of device **200**. Metal gate structures **702** each include a gate dielectric **704** (for example, a gate dielectric layer) and a gate electrode **706** (for example, a work function layer or layer(s) and a bulk conductive layer). Metal gate structures **702** may include numerous other layers, such as capping layers, interface layers, diffusion layers, barrier layers, hard mask layers, or combinations thereof. Gate dielectric layer **704** may include a high-k dielectric layer, for example, a dielectric material having a dielectric constant that is greater than that of silicon dioxide ( $k \approx 3.9$ ). Exemplary compositions for the high-k gate dielectric layer include HfO<sub>2</sub>, HfSiO, HfSiO<sub>4</sub>, HfSiON, HfLaO, HfTaO, HfTiO, HfZrO, HfAlO<sub>x</sub>, ZrO, ZrO<sub>2</sub>, ZrSiO<sub>2</sub>, AlO, AlSiO, Al<sub>2</sub>O<sub>3</sub>, TiO, TiO<sub>2</sub>, LaO, LaSiO, Ta<sub>2</sub>O<sub>3</sub>, Ta<sub>2</sub>O<sub>5</sub>, Y<sub>2</sub>O<sub>3</sub>, SrTiO<sub>3</sub>, BaZrO, BaTiO<sub>3</sub> (BTO), (Ba, Sr)TiO<sub>3</sub> (BST), Si<sub>3</sub>N<sub>4</sub>, hafnium dioxide-alumina (HfO<sub>2</sub>—Al<sub>2</sub>O<sub>3</sub>) alloy, other suitable high-k dielectric material for metal gate stacks, or combinations thereof. The high-k dielectric layer is formed by any suitable processes, such as ALD, CVD, PVD, oxidation-based deposition process, other suitable process, or combinations thereof. In some embodiments, gate dielectric layer **704** includes an interfacial layer (e.g., oxide) disposed between the high-k dielectric layer and fin **206**. Gate electrode **706** includes a conductive material, such as polysilicon, aluminum, copper, titanium, tantalum, tungsten, molybdenum, cobalt, TaN, NiSi, CoSi, TiN, WN, TiAl, TiAlN, TaCN, TaC, TaSiN, other conductive material, or combinations thereof. In some embodiments, gate electrode **706** include a work function layer and a bulk conductive layer. The work function layer is a conductive layer tuned to have a desired work function (e.g., an n-type work function or a p-type work function), and the conductive bulk layer is a conductive layer formed over the work function layer. In some embodiments, the work function layer includes n-type work function materials, such as Ti, silver, manganese, zirconium, TaAl, TaAlC, TiAlN, TaC, TaCN, TaSiN, other suitable n-type work function materials, or combinations thereof. In some embodiments, the work function layer includes a p-type work function material, such as ruthenium, Mo, Al, TiN, TaN, WN, ZrSi<sub>2</sub>, MoSi<sub>2</sub>, TaSi<sub>2</sub>, NiSi<sub>2</sub>, WN, other suitable p-type work function materials, or combinations thereof. The bulk (or fill) conductive layer includes a suitable conductive material, such as Al, W, Ti, Ta, polysilicon, Cu, metal alloys, other suitable materials, or combinations thereof. Gate electrode **706** is formed by any of the processes described herein, such as ALD, CVD, PVD, plating, other suitable process, or combinations thereof. After deposition of the gate dielectric and/or gate electrode materials, the structure may be etched back to



provide a remaining opening **602'**. In some implementations, as illustrated in FIGS. **8A** and **8B**, a self-aligned capping layer (SAC) dielectric layer **802** is formed in the opening **602'**. In some embodiments, the metal gate structure **702** provided on the fin **206** is substantially identical in composition to the metal gate structure **702** provided on the hybrid fin **208**. As illustrated above with reference to FIG. **2**, in some implementations, the same gate line provides the metal gate structure **702** of FIGS. **7A** and **7B**. Again, it is noted that in some implementations the gate structure **702** over the hybrid fin **208** does not control or allow current flow within the hybrid fin **208**. The SAC layer **802** may comprise SiN, HfSi, AlON, HfO, LaO, AlO, LaO, ZrN, SiC, ZnO, SiOC, SiOCN, YO, TaCN, ZrSi, SiCN, ZrAlO, TiO, TaO, ZrO, combinations thereof, and/or other suitable materials.

[0036] The method **100** then proceeds to block **114** where the ILD layer deposited in block **110** is recessed. In some embodiments, the ILD layer(s) are recessed to the extent that they are removed from the structure in their entirety. In other embodiments, a patterning process provides for recessing the ILD layer(s) only adjacent the gate structure where a contact feature will be subsequently formed. As illustrated in FIGS. **9A** and **9B**, in some implementations, the ILD layer **606** is removed from the illustrated region adjacent the gate structure **702**. The ILD layer **606** may be removed by suitable selective dry or wet etching processes. In an embodiment, the CESL layer **604** provides an etch stop for the removal of the ILD layer **606**. The removal provides opening **902** over the source/drain regions **502** over the fin **206** and opening **902** in the corresponding region over the hybrid fin **208**. While not illustrated in the cross-sectional view, in some implementations, the openings **902** extend in the cross-sectional direction to the adjacent gate structure (see FIG. **2**).

[0037] The method **100** then proceeds to block **116** where the CESL deposited in block **110** is recessed. In some implementations, the ILD layer and the CESL layer are both recessed in in-situ etching processes. In some embodiments, the CESL is recessed to the extent that it is removed from the structure in its entirety. As illustrated in FIGS. **10A** and **10B**, in some implementations, the CESL **604** is removed. The CESL **604** may be removed by suitable selective dry or wet etching processes. The removal provides expanded opening **902** over the source/drain regions **502** over the fin **206** and expanded opening **902** over the corresponding area over the hybrid fin **208**.

[0038] The method **100** then proceeds to block **118** where the spacer element(s) are pulled-back (e.g., etched to remove or reduce in thickness). In some implementations, the pull-back includes etching the spacer element(s) such that at least one spacer layer is decreased in width and/or removed. Referring to the example of FIGS. **11A** and **11B**, the spacer element **218B** is removed from the structure. In an embodiment, the spacer element **218B** is an oxide spacer material and the etching process to remove the spacer element **218B** is selective to the oxide material. Thus, in some implementations, the etching process leaves the spacer **218A** (and the dielectric layer **208A**) substantially unetched. The pull-back of the spacer elements **218** by removal of spacer layer **218B** again enlarges the respective openings **902**.

[0039] In some implementations, block **118** of the method **100** further includes decreasing a thickness of a remaining spacer layer, exemplified by spacer layer **218A**. FIGS. **12A** and **12B** illustrate a reduced thickness spacer **218A'**. In an embodiment, the etching process reduces the thickness of the spacer layer **218A** between approximately 10% and 90%. While a greater reduction in thickness benefits the formation of a larger opening **902**, if insufficient spacer material remains there may be risks to the protection the sidewalls of the gate structure **702**. In some implementations, the reduction in thickness of spacer layer **218A** is performed after and separate from the removal of spacer layer **218B**. In other implementations, the reduction of thickness of spacer layer **218A** is performed in a single etching process with the removal of the spacer layer **218B**. The etching process may include dry etch such as a reactive ion etch or other plasma assisted etching process, a wet etch, or other suitable etching processes. In some embodiments, approximately 1-10 nanometers of the spacer layer **218A'** remain on the sidewall of the gate structure **702**.

[0040] The method **100** then proceeds to block **120** where the dielectric layer (e.g., high-k dielectric layer) of the hybrid fin is pulled back. In an embodiment, the dielectric layer is a high-k dielectric layer and an etchant selective to the high-k dielectric layer is utilized to reduce the thickness of the dielectric layer. Referring to the example of FIG. **13B**, the dielectric layer **208A** has been etched back to form reduced thickness dielectric layer **208A'**. In some embodiments, a masking element overlays the active fin **206** region during the etch back of the dielectric layer **208A**. Thus, FIG. **13A** illustrates a substantially similar structure to that of FIG. **12A**. In some implementations, the reduction in thickness of the dielectric layer **208A** is performed separately from the formation of the spacer layer **218A'**. In some implementations, the reduction in thicknesses are performed in situ. The etching process may include suitable dry or wet etching processes.

[0041] In an embodiment, the etching process reduces the thickness of dielectric layer **208A** between approximately 10% and 100% (e.g., full removal). In some embodiments, a thickness of  $td1$  remains at the bottom of the layer **208A'** and a thickness  $td2$  remains at the top of the layer **208A'**. Thickness  $td1$  and  $td2$  may differ. Exemplary thicknesses for  $td1$  and/or  $td2$  include approximately 0.5 nm-10 nm. In some implementations, the entire dielectric layer **208A** is removed. In embodiments where a layer **208A'** remains, the layer may be L-shaped adjacent the gate structure **702** and extend contiguously to the adjacent gate structure (see FIG. **2**). Therefore, in some implementations the layer **208A'** can be U-shaped between adjacent gate structures. As illustrated in FIG. **13B**, a horizontal extending portion of the spacer layer **218B'** may extend beyond an edge of the dielectric layer **208A'** forming a non-collinear, stepped-structure edge.

[0042] Having formed an expanded opening adjacent the gate structures through the preceding blocks of the method **100**, the method **100** then proceeds to block **122** where secondary spacers are formed within the expanded opening. The secondary spacers may include a secondary spacer and a sacrificial secondary spacer. In some implementations, the sacrificial secondary spacer is a sacrificial or dummy spacer that defines a region for an air gap as discussed below.

[0043] Referring to the example of FIGS. **14A** and **14B**, a secondary spacer material layer **1402** is formed over the structure. The secondary spacer material layer **1402** may be formed by CVD, physical vapor deposition (PVD), atomic layer deposition (ALD), high density plasma CVD (HDPCVD), metal organic CVD (MOCVD), remote plasma CVD (RPCVD), plasma enhanced CVD (PECVD), low-pressure CVD (LPCVD), atomic layer CVD (ALCVD), atmospheric pressure CVD (APCVD), oxidation, other suitable methods, or combinations thereof. In an embodiment, the secondary spacer material layer **1402** is deposited as a conformal layer. Exemplary compositions of the secondary spacer material layer **1402** include SiN, HfSi, AlON, HfO, LaO, AlO, LaO, ZrN, SiC, ZnO, SiOC, SiOCN, YO, TaCN, ZrSi, SiCN, ZrAlO, TiO, TaO, ZrO, combinations thereof, and/or other suitable materials. The secondary spacer material layer **1402** may have a thickness of between approximately 1 nm-10 nm. The secondary spacer material layer **1402** thickness impacts the capacitance between the gate structure **702** and the subsequently formed contact structure and thus, its thickness may be selected to account for the desired capacitance while also protecting underlying features (e.g., epitaxial feature **502**).

[0044] Referring to the example of FIGS. **15A** and **15B**, a secondary sacrificial spacer layer **1502** is formed over the structure. The secondary sacrificial spacer layer **1502** may subsequently form a dummy spacer that is removed to provide an air gap as discussed below. The secondary sacrificial spacer layer **1502** may be deposited by CVD, physical vapor deposition (PVD), atomic layer deposition (ALD), high density plasma CVD (HDPCVD), metal organic CVD (MOCVD), remote plasma CVD (RPCVD), plasma enhanced CVD (PECVD), low-pressure CVD (LPCVD), atomic layer CVD (ALCVD), atmospheric pressure CVD (APCVD), plating, other suitable methods, or combinations thereof. In an embodiment, the secondary sacrificial spacer layer **1502** is deposited as a conformal layer. Exemplary compositions of the secondary sacrificial spacer layer **1502** include silicon, a-silicon, or other suitable compositions. Exemplary thicknesses of the secondary sacrificial

spacer layer **1502** include approximately 1 nm to approximately 10 nm. As the thickness of the secondary sacrificial spacer layer **1502** defines the region of the air gap, and thus the low-k dielectric region, a greater thickness of the secondary sacrificial spacer layer **1502** provides for a lower capacitance between the gate structure **702** and an adjacent feature, such as the contact structure discussed below. However, the thickness of secondary sacrificial spacer layer can be controlled to avoid impacting the pitch of the devices.

[0045] In some implementations, after deposition of the secondary sacrificial spacer layer, the sacrificial material (e.g., conformal layer) is etched back to remove the secondary sacrificial spacer layer from over the gate structures and form dummy spacer elements on the gate sidewalls.

Referring to the example of FIGS. **16A** and **16B**, the secondary sacrificial spacer layer **1502** is etched back to form dummy spacer elements **1502'**. The etching may include suitable etching processes such as an anisotropic etch. The dummy spacer elements **1502'** extend above the height of the gate electrode **706**. In some implementations, as illustrated in FIG. **16B**, the dummy spacer elements **1502'** include a foot portion, or are L-shaped in their configuration due to the directional etchings and the overhang of the spacers **218'** and thus, the secondary spacer layer **1402**.

[0046] The method **100** then proceeds to block **124** where a contact etch stop layer (CESL) is formed on the structure. The CESL may be substantially similar to as discussed above with reference to block **110**. Referring to the example of FIGS. **17A** and **17B**, a CESL **1702** is formed over the structures on the fin **206** and the hybrid fin **208**. The CESL **1702** may be formed by CVD, physical vapor deposition (PVD), atomic layer deposition (ALD), high density plasma CVD (HDPCVD), metal organic CVD (MOCVD), remote plasma CVD (RPCVD), plasma enhanced CVD (PECVD), low-pressure CVD (LPCVD), atomic layer CVD (ALCVD), atmospheric pressure CVD (APCVD), plating, other suitable methods, or combinations thereof. Exemplary compositions of the CESL **1702** include SiN, HfSi, AlON, HfO, LaO, AlO, LaO, ZrN, SiC, ZnO, SiOC, SiOCN, YO, TaCN, ZrSi, SiCN, ZrAlO, TiO, TaO, ZrO, combinations thereof, and/or other suitable materials. The CESL **1702** may have a thickness of between approximately 1 nm and 10 nm. The thickness may be selected to provide suitable etch stop properties, while considering the impacts to the capacitance between the gate structure **706** and the adjacent contact discussed below. The CESL **1702** may be substantially the same thickness over the fin **26** and the hybrid fin **208**, for example, deposited as a conformal layer.

[0047] The method **100** then proceeds to block **126** where an ILD layer is formed over the structure. The ILD layer may be substantially similar to as discussed above with reference to block **110**. Referring to the example of FIGS. **18A** and **18B**, an ILD **1802** is formed over the structure. The ILD **1802** may be deposited by deposition processes (such as CVD, PVD, ALD, HDPCVD, MOCVD, RPCVD, PECVD, LPCVD, ALCVD, APCVD, FCVD, HARP, HDP, other suitable methods, or combinations thereof). Exemplary compositions of the ILD **1802** include a dielectric material having a dielectric constant that is less than about 2.5 (e.g., ELK), silicon carbide (SiC), carbon-doped oxide (for example, a SiCOH-based material (having, for example, Si—CH<sub>3</sub> bonds)), silicon nitride, silicon oxynitride, and/or other suitable compositions. The ILD layer **1802** may fill the region between adjacent gate structures.

[0048] Block **126** of the method **100** in some implementations may include a planarization process, such as a chemical mechanical polish, of the structure after the ILD deposition. Referring to the example of FIGS. **19A** and **19B**, the structures have been planarized to expose a top surface of the SAC **802** and provide planar surfaces **1902** and **1904** respectively. The planar surface **1902** is defined by the SAC **802**, the spacer **218A'**, the first spacer **1402**, the dummy spacer element **1502'**, the CESL **1702**, and the ILD **1802**. The planar surface **1904** is defined by the SAC **802**, the spacer **218A'**, the first spacer **1402**, the CESL **1702**, and the ILD **1802**.

[0049] The method **100** then proceeds to block **128** where a contact structure is formed adjacent the gate structures. The contact structure may be formed to interface and provide a connection to the source/drain feature of the active area. Referring to the example of FIGS. **20A** and **20B**, a contact

feature **2002** is formed to the source/drain region **502** over the fin **206**. Similar in structure, the contact feature **2002** is formed adjacent the gate structure **702** over the hybrid fin **208**. Here, the contact structure may interface the dielectric layer **208A**, for example, high-k dielectric. In some implementations, the contact structure **2002** over the hybrid fin **208** does not provide for conducting an electrical signal to a feature on the hybrid fin **208**, but is a dummy structure.

[0050] The contact structure **2002** may include one or more electrically conductive materials, such as tungsten, ruthenium, cobalt, copper, aluminum, iridium, palladium, platinum, nickel, other low resistivity metal constituent, alloys thereof, silicide, or combinations thereof. The conductive material(s) can be deposited by PVD, CVD, ALD, electroplating, electroless plating, other suitable deposition process, or combinations thereof. The contacts **2002** may include a multi-layer structure such as a barrier layer, adhesion layer, bulk layer, and/or other suitable layers.

[0051] After formation of the contact structure **2002**, the structure may be further planarized for example by a chemical mechanical polish. In some implementations, the planarization exposes the dummy spacer **1502'** including over the hybrid fin **208** as shown in FIG. **20B**.

[0052] The method **100** then proceeds to block **130** where the dummy spacer element is selectively removed to form an air gap. The dummy spacer is removed over both the active fin and the hybrid fin, in some implementations, concurrently. Referring to the example of FIGS. **21A** and **21B**, the dummy spacer **1502'** is removed to form air gap **2102**. It is noted that while the illustration shows the entire removal of the dummy spacer **1502'**, in some implementations, a residue of spacer material remains for example at a bottom of the air gap **2102**. The removal of the dummy spacer **1502'** may be performed by suitable selective etching process such as a dry etch or wet etch process.

[0053] The air gap **2102** may have a width,  $w_{\text{sub.a}}$ , of between approximately 1 nanometer and approximately 10 nanometers. The width  $w_{\text{sub.a}}$  of the air gap **2102** affects the capacitance between the gate structure and the subsequently formed contact feature and thus, the greater the width, the larger the low-k dielectric region thereby providing for further capacitance improvement. Should the thickness become too great however, the pitch and structural integrity may be impacted. The secondary spacer layer **1402** may have a thickness  $w_s$  under the air gap **2102** of between approximately 1 nm and approximately 10 nm. In some implementations, the thickness of the secondary spacer **1402** at the sidewall may also be between 1 and 10 nm. The thickness of the secondary spacer **1402** may be selected to provide suitable protection for underlying features, while limiting its impact on the capacitance performance improvements gained by the air gap **2102**. In an embodiment, the air gap **2102** over the hybrid fin **208** includes a foot portion, or is L-shaped in configuration. The foot portion may have a thickness (i.e., vertically measured) substantially similar to the thickness of the air gap **2102** along the sidewall (i.e., horizontally measured).

[0054] The method **100** then proceeds to block **132** where a seal layer is formed over the air gap of block **130**. Referring to the example of FIGS. **22A** and **22B**, a seal material layer **2202** is deposited over the structure. The seal material layer **2202** may be deposited by CVD, physical vapor deposition (PVD), atomic layer deposition (ALD), high density plasma CVD (HDPCVD), metal organic CVD (MOCVD), remote plasma CVD (RPCVD), plasma enhanced CVD (PECVD), low-pressure CVD (LPCVD), atomic layer CVD (ALCVD), atmospheric pressure CVD (APCVD), plating, other suitable methods, or combinations thereof. Exemplary compositions of the seal layer include SiN, HfSi, AlON, HfO, LaO, AlO, LaO, ZrN, SiC, ZnO, SiOC, SiOCN, YO, TaCN, ZrSi, SiCN, ZrAlO, TiO, TaO, ZrO, combinations thereof, and/or other suitable compositions. After deposition of the seal material layer **2202**, an etching back or planarization process may be performed to remove the overfill of the seal material layer **2202** and provide seal features **2202'** as illustrated in FIGS. **23A** and **23B**. In some implementations, the depth of the seal feature **2202'**, denoted  $d_{\text{sub.s}}$ , is between approximately 1 nm and approximately 10 nm. The seal features **2202'** may be of sufficient thickness to protect the air gap **2102** during the deposition of overlying layer, but thin enough to allow for the air gap **2102** to extend along the length of the gate electrode **706**.

[0055] In some implementations at this point in the fabrication process and/or in the final device, the SAC **802** has been processed to provide a thickness of H.sub.SAC between approximately 1 nanometer and 30 nanometers. In other implementations, and/or at other portions of the structure, the SAC **802** has been eliminated. In some, the SAC **802** has a width of w.sub.SAC between approximately 2 nanometers and 50 nanometers. In other implementations, and/or at other portions of the structure, the SAC **802** has been eliminated. w.sub.SAC and H.sub.SAC may be substantially similar between the structure over the fin **206** and the structure over the hybrid fin **208**. The dimensions of the SAC **802** may be selected to provide suitable protection of the gate electrode **706**, isolation between adjacent conductive features (e.g., gate structures), and/or provide surrounding insulating material for a subsequently formed gate contact structure which extends therethrough.

[0056] The structures of FIGS. **23A** and **23B** are illustrative of the air gap **2102** interposing the gate electrode **706** and the contact **2002**, two conductive structures. The air gap **2102** provides air, a low dielectric constant medium (air having a k-value of approximately 1) interposing the features. The low dielectric constant allows for a reduction of capacitance between the two features, in comparison with a high-k dielectric material. Thus, the method **100** provision of a reduction of the amount of high-k material of the hybrid fin **208A** (e.g., exemplified by the etch back step above and/or the air gap **2102**) and the method **100**'s introduction of a low-k medium of air can provide for device performance improvement. Specifically, the method **100** and device **200** in some implementations allows for lowering the coupling capacitance between the two conductive features in comparison with, for example, additional high-k material of the hybrid fin **208A** interposing said features. Lowering the capacitance provides for device performance enhancement including providing a higher operating speed device.

[0057] The method **100** may proceed to block **134** where fabrication continues including forming additional layers of the MLI over the gate structure and contact features of the structure. Referring to the example of FIGS. **24A** and **24B**, in some implementations, the contact **2002** is recessed and a second capping layer SAC **2406** is disposed over the contact **2002**. The SAC **2406** may include SiN, HfSi, AlON, HfO, LaO, AlO, LaO, ZrN, SiC, ZnO, SiOC, SiOCN, YO, TaCN, ZrSi, SiCN, ZrAlO, Tio, TaO, ZrO, combinations thereof, and/or other suitable materials. The thickness of the SAC **2406** may be between approximately 1 and 50 nm. The thickness of the SAC **2406** provides for isolation region within which an interconnect can be formed and determines the contact resistance of the feature **2002**. In other embodiments, the SAC **2406** is omitted. The SAC **2406** may be substantially similar as disposed over the hybrid fin **208** and as disposed over the fin **206**.

[0058] In some implementations of the method **100**, an etch stop layer (ESL) **2402** and/or an ILD layer **2404** may be disposed over the structure. The ESL **2402** and/or ILD layer **2404** may form a portion of an MLI of the device **200**. The ESL **2402** may include a different material than the ILD layer **2404**. In some implementations, the ESL **2402** includes silicon nitride, silicon oxide, silicon oxynitride, silicon carbide or other suitable material that functions to stop the etching of the subsequent etching process(es). The ILD layer **2404** may be substantially similar to the ILD layers **606** and/or **1802** discussed above. The method may continue to form conductive interconnect features of the MLI extending through the ESL **2402** and ILD layer **2404** to the contact features **2002**. Exemplary interconnect features of a conductive via **2502** providing an interconnection to the gate structure **702** and a conductive via **2504** providing an interconnection to the contact feature **2002** are illustrated in FIGS. **25A** and **25B**. Again, it is noted that the interconnect features interfacing the hybrid fin features may be dummy features such that they do not carry a current to an active device on the hybrid fin. These features over the hybrid fin may be provided nonetheless for process uniformity and avoidance of loading effects (e.g., lithography, etching).

[0059] The conductive vias **2502** and **2504** may be filled with one or more electrically conductive materials, such as tungsten, ruthenium, cobalt, copper, aluminum, iridium, palladium, platinum, nickel, other low resistivity metal constituent, alloys thereof, or combinations thereof. The

conductive material(s) can be deposited by PVD, CVD, ALD, electroplating, electroless plating, other suitable deposition process, or combinations thereof. After deposition, a planarization process may remove excess conductive material. The conductive vias **2502** and **2504** may include a multi-layer structure such as a barrier layer, adhesion layer, bulk layer, and/or other suitable layers.

[0060] FIGS. **26A** and **26B** illustrate an alternative embodiment of a device **200'**. While substantially similar to the device **200** illustrated in the previous figures and similarly fabricated according to the steps of the method **100** as discussed above, the device **200'** illustrates that in some implementation in forming the contact structures **2002**, a portion of the ILD layer **1802'** may remain between the contact structure **2002** and the CESL **1702**. The residual ILD layer **1802'** may be provided on side of the gate structure **702** and removed from an opposing side as illustrated, or may be present on both sides of the gate structure **702**. Similarly, the residual ILD layer **1802'** may be present over the hybrid fin **208** and removed over the fin **206**, or vice versa.

[0061] FIGS. **27A** and **27B** illustrate an alternative embodiment of the device **200''**. While substantially similar to the device **200** illustrated in the previous figures and similarly fabricated according to the method **100** discussed above, the device **200''** illustrates that in some implementations, a residual portion of the dummy spacer element **1502''** may remain, for example over the hybrid fin **208**. The residual portion **1502''** may interface the first spacer **1402**, the CESL **1702**, and/or the air gap **2102**. In some implementations, the residual portion **1502''** causes the shape of the air gap **2102** to not include a foot or L-shaped configuration, but be substantially rectangular in shape.

[0062] The device **200''** also is illustrative of an offset conductive via **2504'**. The offset conductive via **2504'** may be misaligned due to processing tolerances, design choices, and/or other recognized or unrecognized causes. The offset conductive via **2504'** may interface a top portion of the CESL **1702** and/or the seal **2202'**.

[0063] Thus, in some of the embodiments provided herein, an air gap provides a region of a low-k dielectric interposing conductive features that may reduce the capacitance of the device. In particular, in some embodiments, the air gap region is provided in lieu of some or all of the high-k dielectric material of a hybrid fin. In some implementations, the air gap region is provided over the hybrid fin and between features formed on the hybrid fin.

[0064] Thus, one of the embodiments of the present disclosure described is a method that includes forming a fin structure and a hybrid fin structure over a substrate. The hybrid fin structure comprises a dielectric material. A gate structure is formed over the fin structure and the hybrid fin structure. A dummy spacer feature is provided adjacent the gate structure and over the hybrid fin structure. A contact element is provided over the hybrid fin structure. The dummy spacer feature interposes the gate structure and the contact element. The method includes removing the dummy spacer feature to form an air gap.

[0065] In an embodiment, the method further includes forming a first spacer between the dummy spacer feature and the gate structure over the hybrid fin structure. In an implementation, after providing the dummy spacer feature and prior to providing the contact element, a contact etch stop layer is deposited over the dummy spacer feature. In some implementations of the method, forming the hybrid fin structure includes forming a fin structure having a bottom layer and a top layer. The top layer may be a high-k dielectric material. In a further embodiment, a dummy gate structure is formed over the top layer of the hybrid fin structure. A region of the high-k dielectric material of the hybrid fin structure adjacent the dummy gate structure is etched and after the etching, the dummy gate structure is removed and the gate structure is provided. In an embodiment, removing the dummy gate structure includes etching the top layer of the hybrid fin structure to expose the bottom layer of the hybrid fin structure. In a further embodiment, the top layer of the hybrid fin structure is thinned after the removing the dummy gate structure and after the region of the high-k dielectric adjacent the dummy gate structure is etched. In an embodiment, removing the dummy spacer feature to form the air gap forms a first air gap over the hybrid fin structure and a second air

gap over the fin structure. In a further embodiment, a seal layer is formed over the air gap. [0066] In another of the broader embodiments of the method, the method includes forming an active fin structure and a dielectric fin structure over a substrate. The dielectric fin structure comprises a layer of high-k dielectric material. The method may further include providing a first dummy gate structure over the active fin structure and a second dummy gate structure over the layer of high-k dielectric material of the dielectric fin structure. Source/drain regions of the active fin structure and the dielectric fin structure adjacent the first and second dummy gate structures respectively are recessed. The method proceeds to include removing the first dummy gate structure to expose a channel region of the active fin structure and removing the second dummy gate structure. Removing the second dummy gate structure etches an opening in the layer of high-k dielectric material. A first metal gate structure is formed over the channel region of the active fin structure and forming a second metal gate structure within the opening in the layer of high-k dielectric material. After forming the second metal gate structure, the method may include reducing a thickness of the layer of high-k dielectric material adjacent the second metal gate structure. A conductive contact is formed over the dielectric fin structure and spaced a distance from the second metal gate structure and an air gap structure is formed in the distance.

[0067] In a further embodiment the method also includes, after providing the first dummy gate structure and the second dummy gate structure, forming a first ILD layer; and also after forming the first metal gate structure and forming the second metal gate structure, removing the first ILD layer from over the active fin structure and the dielectric fin structure. The removing the first ILD layer provides an opening exposing the layer of high-k dielectric material for performing the reducing the thickness of the layer of the high-k dielectric material. In some implementations the method includes forming a dummy spacer element in the opening and subsequently removing the dummy spacer element to form the air gap structure.

[0068] In an embodiment, the method includes forming a second ILD in the opening after the reducing the thickness of the layer of the high-k dielectric material. In some implementations, forming the air gap structure includes removing a dummy spacer layer disposed over the layer of high-k dielectric material having the reduced thickness.

[0069] In another of the broader embodiments, a semiconductor device is provided that includes a first gate structure over an active fin structure and a second gate structure over a dielectric fin structure. A conductive structure is placed over the dielectric fin structure and spaced a distance from the second gate structure. A plurality of dielectric layers is formed in the distance. The plurality of dielectric layers include a high-k dielectric layer abutting sidewalls of the second gate structure; a first spacer element adjacent the high-k dielectric layer; an air gap adjacent the first spacer element; and a contact etch stop layer (CESL).

[0070] In a further embodiment, the device includes a seal layer on a top of the air gap and extending between the CESL and the first spacer element. In an embodiment, the dielectric fin structure includes another dielectric layer interfacing the second gate structure and the high-k dielectric layer. In an embodiment, the air gap has an L-shape. In some implementations, another air gap is disposed between the first gate structure and another conductive structure disposed over the active fin structure. The another conductive structure is a contact to a source/drain region adjacent the first gate structure in some implementations.

[0071] The foregoing outlines features of several embodiments so that those skilled in the art may better understand the aspects of the present disclosure. Those skilled in the art should appreciate that they may readily use the present disclosure as a basis for designing or modifying other processes and structures for carrying out the same purposes and/or achieving the same advantages of the embodiments introduced herein. Those skilled in the art should also realize that such equivalent constructions do not depart from the spirit and scope of the present disclosure, and that they may make various changes, substitutions, and alterations herein without departing from the spirit and scope of the present disclosure.

## Claims

1. A semiconductor device, comprising: a first gate structure over an active fin structure and a second gate structure over a dielectric fin structure; and a conductive structure over the dielectric fin structure and spaced a distance from the second gate structure, wherein a plurality of dielectric layers is formed in the distance including: a high-k dielectric layer abutting sidewalls of the second gate structure; a first spacer element adjacent the high-k dielectric layer; an air gap adjacent the first spacer element; and a contact etch stop layer (CESL).
2. The semiconductor device of claim 1, further comprising: a seal layer on a top of the air gap and extending between the CESL and the first spacer element.
3. The semiconductor device of claim 1, wherein the dielectric fin structure includes another dielectric layer interfacing the second gate structure and the high-k dielectric layer.
4. The semiconductor device of claim 1, wherein the air gap has an L-shape.
5. The semiconductor device of claim 1, further comprising: another air gap between the first gate structure and another conductive structure disposed over the active fin structure.
6. The semiconductor device of claim 5, wherein the another conductive structure is a contact to a source/drain region adjacent the first gate structure.
7. The semiconductor device of claim 1, wherein the air gap extends from CESL to the first spacer element.
8. The semiconductor device of claim 1, wherein the air gap has an L-shape in a cross-sectional view, wherein the L-shape is defined by an edge of the CESL.
9. A semiconductor structure comprising: an active structure raised above a substrate and a dielectric pedestal structure raised above the substrate, wherein the active structure and the dielectric pedestal extend in a first direction in a top view; a first metal gate structure over a channel region of the active structure and a second metal gate structure over the dielectric pedestal structure, wherein the first metal gate structure and the second metal gate structure extend in a second direction in the top view; an L-shaped air gap disposed adjacent to the second metal gate structure and a rectangular-shaped air gap disposed adjacent the first metal gate structure over the channel region, wherein the L-shaped air gap and the rectangular-shaped air gap are defined in a cross-sectional view; and a first conductive via extending to the first metal gate structure and a second conductive via extending to the second metal gate structure in the cross-sectional view.
10. The semiconductor structure of claim 9, further comprising: a contact element over the dielectric pedestal structure, wherein the L-shaped air gap interposes the contact element and the second metal gate structure in the cross-sectional view.
11. The semiconductor structure of claim 10, further comprising: a contact etch stop layer (CESL) interposing the contact element and the L-shaped air gap in the cross-sectional view.
12. The semiconductor structure of claim 10, further comprising: a conductive via extending to an upper surface of the contact element.
13. The semiconductor structure of claim 12, further comprising: another conductive via extending to a top surface of the second metal gate structure, wherein the another conductive via is coplanar with the conductive via.
14. A semiconductor device, comprising: a first gate structure over an active structure and a second gate structure over a dielectric fin structure; a first conductive structure adjacent to and spaced a first distance from the first gate structure, wherein a first plurality of dielectric layers is formed in the first distance including: a first spacer element along sidewalls of the first gate structure; a second spacer element adjacent the first spacer element; a first air gap adjacent the second spacer element; and a contact etch stop layer (CESL); a second conductive structure over the dielectric fin structure and spaced a second distance from the second gate structure, wherein a second plurality of dielectric layers is formed in the second distance including: a high-k dielectric layer along



sidewalls of the second gate structure; a third spacer element adjacent the high-k dielectric layer; a second air gap adjacent the second spacer element; and the contact etch stop layer (CESL).

**15.** The semiconductor device of claim 14, wherein the third spacer element is a same material as the second spacer element.

**16.** The semiconductor device of claim 14, wherein the first air gap has an uppermost edge higher than an uppermost surface of the first gate structure.

**17.** The semiconductor device of claim 14, wherein the uppermost edge of the first air gap is coplanar with an uppermost edge of the second air gap.

**18.** The semiconductor device of claim 14, wherein the first air gap is a rectangular shape in a cross-sectional view and the second air gap is an L-shape in the cross-sectional view.

**19.** The semiconductor device of claim 14, wherein the first air gap has a substantially constant width from an uppermost edge to a lowermost edge.

**20.** The semiconductor device of claim 19, wherein the second air gap has an L-shape having a footer portion with a greater width than an upper portion.

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